## Features

- Broadband Performance
- Low Loss @ 2.7 GHz :

$$
\begin{aligned}
& \mathrm{TX}=0.25 \mathrm{~dB} \\
& \mathrm{RX}=0.35 \mathrm{~dB}
\end{aligned}
$$

- High Isolation @ 2.7 GHz :

$$
\mathrm{RX}=44 \mathrm{~dB}
$$

- Power Handling @ 2.7 GHz :

$$
200 \text { W CW @ }+85^{\circ} \mathrm{C}
$$

$$
122 \text { W CW @ }+120^{\circ} \mathrm{C}
$$

- Lead-Free 5 mm 20-Lead HQFN Package
- RoHS* Compliant
- Designed for High Power TDD-LTE Applications


## Description

The MASW-011120 is a SPDT high power, broadband, high linearity, PIN diode T/R switch for $0.03-6.0 \mathrm{GHz}$ high power applications. The device is provided in an industry standard lead free 5 mm HQFN plastic package.

This device incorporates PIN diode die fabricated with a low loss, high isolation switching diode process.

MASW-011120 can be used in any application requiring a low-loss, high-isolation, and high-powerhanding SPDT.

## Ordering Information ${ }^{1,2}$

| Part Number | Package |
| :---: | :---: |
| MASW-011120-TR1000 | 1000 Piece Tape and Reel |
| MASW-011120-TR3000 | 3000 Piece Tape and Reel |
| MASW-011120-SMB | Sample Board |

[^0]
## Functional Schematic



## Pin Configuration ${ }^{3}$

| Pin \# | Pin Name | Function |
| :---: | :---: | :---: |
| $1,4,5,7,11,19$ | GND | Ground |
| $2,6,8,10,13,14$, <br> $15,16,18,20$ | N/C | No Connection |
| 3 | ANT | RF Port |
| 9 | RX | RF Port |
| 12 | RX BIAS | RX Bias Input |
| 17 | TX | RF Port |
| 21 | Paddle | Ground ${ }^{4}$ |

3. MACOM recommends connecting all No Connection (N/C) pins to ground.
4. The exposed pad centered on the package bottom must be connected to RF, DC and thermal ground.
[^1]
## Electrical Specifications:

Freq. $=2.7 \mathrm{GHz}, 3.5 \mathrm{GHz}, \mathrm{T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}, \mathrm{Z}_{0}=50 \Omega$, Bias $=60 \mathrm{~V} / 0 \mathrm{~V}$. See Bias Table.

| Parameter | Test Conditions | Units | Min. | Typ. | Max. |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Insertion Loss | ANT to TX ON @ 2.7 GHz ANT to TX ON @ 3.5 GHz ANT to RXON @ 2.7 GHz ANT to RX ON @ 3.5 GHz | dB | - | $\begin{aligned} & 0.25 \\ & 0.30 \\ & 0.35 \\ & 0.50 \end{aligned}$ | $\begin{aligned} & 0.45 \\ & 0.50 \\ & 0.60 \\ & 0.70 \end{aligned}$ |
| Isolation | ANT to RX (TX ON) @ 2.7 GHz ANT to RX (TX ON) @ 3.5 GHz ANT to TX (RX ON) @ 2.7 GHz ANT to TX (RX ON) @ 3.5 GHz | dB | $\begin{aligned} & 35 \\ & 35 \\ & 12 \\ & 10 \end{aligned}$ | $\begin{aligned} & 44 \\ & 44 \\ & 15 \\ & 13 \end{aligned}$ | - |
| ANT Return Loss | ANT to RX ON ANT to TX ON | dB | - | $\begin{aligned} & 23 \\ & 25 \end{aligned}$ | - |
| TX Return Loss | ANT to TX ON | dB | - | 22 | - |
| RX Return Loss | ANT to RX ON | dB | - | 26 | - |
| Input P0.1 dB ${ }^{5}$ | ANT to TX ON | dBm | - | 51 | - |
| IIP3 TX | ANT to TX, $\mathrm{P}_{\text {IN }}=30 \mathrm{dBm}$ | dBm | - | 68 | - |
| IIP3 RX | ANT to RX, $\mathrm{P}_{\text {IN }}=30 \mathrm{dBm}$ | dBm | - | 68.5 | - |
| RF Input Power $\mathrm{CW}^{5}$ <br> ANT to TX ON | $85^{\circ} \mathrm{C}$ @ $2.7 \mathrm{GHz} ; 100 \mathrm{~mA}$ $85^{\circ} \mathrm{C}$ @ $2.7 \mathrm{GHz} ; 200 \mathrm{~mA}$ $120^{\circ} \mathrm{C}$ @ $2.7 \mathrm{GHz} ; 100 \mathrm{~mA}$ $120^{\circ} \mathrm{C}$ @ $2.7 \mathrm{GHz} ; 200 \mathrm{~mA}$ | W | - | $\begin{gathered} 145 \\ 200 \\ 97 \\ 122 \end{gathered}$ | - |
| Switching Speed <br> TX Ton <br> TX Toff <br> RX $T_{\text {ON }}$ <br> RX Toff | $\mathrm{T}_{\text {ON }}-50 \%$ control to $90 \% \mathrm{RF}$ <br> Toff $-50 \%$ control to $10 \%$ RF | $\mu \mathrm{s}$ | - | $\begin{aligned} & 0.5 \\ & 1.6 \\ & 0.3 \\ & 0.3 \end{aligned}$ | - |
| Group Delay | - | ns | - | 50 | - |
| In-band Ripple | $\begin{gathered} 20 \mathrm{MHz} \\ 200 \mathrm{MHz} \end{gathered}$ | dB | - | $\begin{gathered} 0.05 \\ 0.1 \\ \hline \end{gathered}$ | - |

5. Maximum source and load VSWR < 1.2:1.

## Bias Table

| Bias Table | TX | RX | RX BIAS | ANT |
| :--- | :---: | :---: | :---: | :---: |
| Pin | $\mathbf{1 7}$ | $\mathbf{9}$ | $\mathbf{1 2}$ | $\mathbf{3}$ |
| ANT to TX ON (Insertion Loss) | $(\mathrm{GND}),-100 \mathrm{~mA}^{6}$ | $(+60 \mathrm{~V}), 10 \mathrm{~mA}^{6}$ | $(\mathrm{GND}),-10 \mathrm{~mA}^{6}$ | $+5 \mathrm{~V}, 100 \mathrm{~mA}^{6}$ |
| ANT to RX (Isolation) | $(\mathrm{GND}),-100 \mathrm{~mA}^{6}$ | $(+60 \mathrm{~V}), 10 \mathrm{~mA}^{6}$ | $(\mathrm{GND}),-10 \mathrm{~mA}^{6}$ | $+5 \mathrm{~V}, 100 \mathrm{~mA}^{6}$ |
| ANT to RX ON (Insertion Loss) | $(+60 \mathrm{~V}), 0 \mathrm{~mA}$ | $(\mathrm{GND}),-100 \mathrm{~mA}^{6}$ | $(+60 \mathrm{~V}), 0 \mathrm{~mA}$ | $+5 \mathrm{~V}, 100 \mathrm{~mA}^{6}$ |
| ANT to TX (Isolation) | $(+60 \mathrm{~V}), 0 \mathrm{~mA}$ | $(G N D),-100 \mathrm{~mA}^{6}$ | $(+60 \mathrm{~V}), 0 \mathrm{~mA}$ | $+5 \mathrm{~V}, 100 \mathrm{~mA}^{6}$ |

[^2]Maximum Operating Conditions ${ }^{7}$

| Parameter | Operating Maximum |
| :---: | :---: |
| TX Forward Current | 250 mA |
| RX Forward Current | 250 mA |
| Reverse Voltage (RF \& DC) | 200 V |
| ANT to TX Power CW | See Power Derating Curve |
| ANT to TX Peak Power <br> (LTE Signal) | 1000 W |
| Junction Temperature ${ }^{8,9}$ | $+175^{\circ} \mathrm{C}$ |
| Case (Paddle) Temperature | $-40^{\circ} \mathrm{C}$ to $+120^{\circ} \mathrm{C}$ |
| Storage Temperature | $-55^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |

7. Exceeding these limits may cause permanent damage.
8. MACOM does not recommend sustained operation near these survivability limits.
9. Operating at nominal conditions with $\mathrm{T}_{J} \leq+175^{\circ} \mathrm{C}$ will ensure MTTF > $1 \times 10^{6}$ hours.

## Handling Procedures

Please observe the following precautions to avoid damage:

## Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

| Parameter | Rating | Standard |
| :---: | :---: | :---: |
| Human Body | 500 V | ESDA / JEDEC |
| Model (HBM) | (Class 1B) | JS-001 |
| Charged Device <br> Model (CDM) | 2000 V | JEDEC |
| (Class C7) | JESD22-C101 |  |

## Typical Performance Curves

ANT to TX Input Power Derating Curve @ 2.7 GHz


ANT to TX Input Power Derating Curve over Reverse Bias Voltage @ 2.7 GHz


ANT to TX Input Power Derating Curve over Frequency @ $120^{\circ} \mathrm{C}$ Case Temp


## Typical Performance Curves over Temperature

All plots herein are taken with bias per the Bias Table on Page 2 unless otherwise specified.
S-parameters were measured using G-S-G probes on a sample board; reference planes are at the part's RF ports. The sample board and its layer stack-up are on page 7


ANT to TX Insertion Loss


## ANT Return Loss in TX ON state



ANT to RX Insertion Loss


ANT Return Loss in RX ON state


RX Return Loss in RX ON state


## Typical Performance Curves over Temperature

TX Return Loss in TX ON state


ANT to TX Isolation in RX ON state


ANT to TX Insertion Loss over Current @ $25^{\circ} \mathrm{C}$


ANT to RX Isolation in TX ON state @ 100 mA


ANT to RX Isolation in TX ON state, over RX Bias Current @ $25^{\circ} \mathrm{C}$


ANT to RX Insertion Loss over Current @ $25^{\circ} \mathrm{C}$


## Sample Board



Optional part for probing, provided per request

## PCB Layout Stack-Up



Dimensions are in inches.

To use the sample board: bias VCC at 5 V (current will be limited to 100 mA by on-board resistors R1, R2) and bias RX and TX according to the control table on page 8.

## Sample Board Schematic (parts list on page 9)



## Control Table

| Configuration | VCC | RX | TX/RX_Bias |
| :---: | :---: | :---: | :---: |
| TX ON <br> RX OFF | $5 \mathrm{~V}(100 \mathrm{~mA})$ | $60 \mathrm{~V}(10 \mathrm{~mA})$ | GND |
| TX OFF <br> RX ON | $5 \mathrm{~V}(100 \mathrm{~mA})$ | GND | 60 V |

Parts List

| Component ID | Value | Package | Mfg. Par\#\# | Spec |
| :---: | :---: | :---: | :---: | :---: |
| U1 | - | HQFN-20LD 5 mm | MASW-011120 | - |
| L1, L2, L3, L4 | 33 nH | 0603 | LQW18AN33NJ8ZD | $>200 \mathrm{~mA}$ |
| C1, C3, C7 ${ }^{10}$ | 10 pF | 0505 | $800 \mathrm{~A} 100 \mathrm{JT250X}$ | High Freq |
| C2, C4, C6,C8, C12 | 22 pF | 0603 | 600 S220FT250XT | High Freq |
| C24 | $1 \mu \mathrm{~F}$ | 0805 | C2012X7S2A105K125AB | High Freq |
| R1, R2 | $20 \Omega$ | 1206 | CRCW120620R0FKEA | 0.25 W |
| R3, R4 | $2.37 \mathrm{k} \Omega$ | 1210 | ERJ-14NF2371U | - |
| R6, R10 | $0 \Omega$ | 0603 | - | - |
| J1-J5 | RF CONN | SMA | $142-0761-821$ | - |
| J6 | DC CONN | $10-\mathrm{pin}$ | - | Surmount |

10. Required vertical mounting orientation of $\mathrm{C} 1, \mathrm{C} 3, \& \mathrm{C} 7$. Noted on PCB Layout on page 7.


Horizontal Electrode Orientation


Vertical
Electrode Orientation

## Typical Performance Curves on the Sample Board over Temperature

ANT to TX Insertion Loss (PCB loss de-embedded)


## ANT Return Loss in TX ON state



## TX Return Loss in TX ON state



ANT to RX Insertion (PCB loss de-embedded)


ANT Return Loss in RX ON state


RX Return Loss in RX ON state


## Typical Performance Curves on the Sample Board over Temperature

ANT to TX Insertion Loss over Current @ $25^{\circ} \mathrm{C}$, PCB Loss De-embedded


ANT to TX Isolation


ANT to RX Insertion Loss over Current @ $25^{\circ} \mathrm{C}$, PCB Loss De-embedded


ANT to RX Isolation


ANT to RX Isolation over Current @ $25^{\circ} \mathrm{C}$


## Lead-Free 5 mm 20-Lead HQFN ${ }^{\dagger}$



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[^0]:    1. Reference Application Note M513 for reel size information.
    2. All sample boards include 3 loose parts.
[^1]:    * Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

[^2]:    6. Currents level comply with the schematic on page 8.
[^3]:    ${ }^{\dagger}$ Reference Application Note S2083 for lead-free solder reflow recommendations. Meets JEDEC moisture sensitivity MSL level 1 requirements. Plating is NiPdAuAg.

